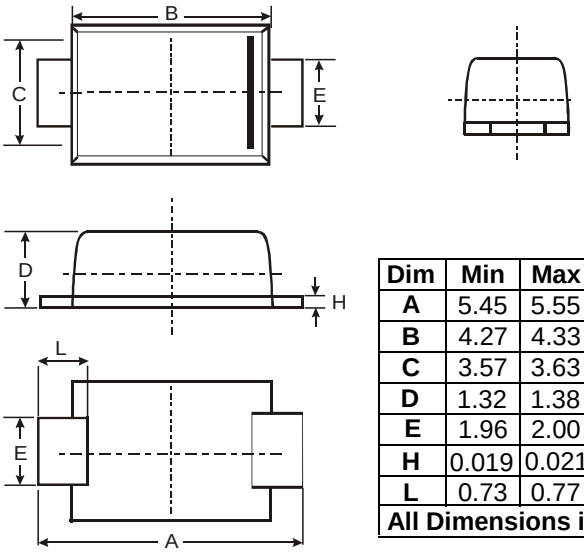
CURRENT 3.0 Ampere
VOLTAGE RANG 50 to 1000 Volts

RS3ABF THRU RS3MBF

S M B F

FEATURES

- Glass Passivated chip junction
- Built-in strain relief
- Fast switching speed for high efficiency
- High temperature soldering guaranteed: 250 /10 second at terminals



Dim	Min	Max	Typ
A	5.45	5.55	5.50
B	4.27	4.33	4.30
C	3.57	3.63	3.60
D	1.32	1.38	1.35
E	1.96	2.00	1.98
H	0.019	0.021	0.20
L	0.73	0.77	0.75
All Dimensions in mm			

MECHANICAL DATA

- Case: Transfer molded plastic
- Epoxy: UL 94V-0 rate flame retardant
- Lead: Solder plated, solderable per MIL-STD-202E method208C
- Polarity: Color band denotes cathode end
- Weight: 0.002ounce, 0.09 gram

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

- Ratings at 25 ambient temperature unless otherwise specified.
- Single phase, half wave, 60Hz, resistive or inductive load.
- For capacitive load derate current by 20%.

	SYMBOLS	RS3A	RS3B	RS3D	RS3G	RS3J	RS3K	RS3M	UNIT
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current at T_L=100	$I_{(AV)}$	3.0							Amps
Peak Forward Surge Current 8.3ms single half sine wave superimposed on rated load (JEDEC Method)	I_{FSM}	100							Amps
Maximum Instantaneous Forward Voltage at 3.0A	V_F	1.3							Volts
Maximum DC Reverse Current at rated DC blocking voltage at T_A = 25	I_R	10.0							A
Maximum DC Reverse Current at rated DC blocking voltage at T_A = 125	I_R	250							A
Typical Reverse Recovery Time Test conditions I_F=0.5A, I_R=1.0A, I_{RR}=0.25A	T_{rr}	150				250	500		ns
Typical Junction Capacitance (NOTE 2)	C_J	60							pF
Typical Thermal Resistance (NOTE 1)	$R_{\theta JA}$	50							/W
Typical Thermal Resistance (NOTE 1)	$R_{\theta JL}$	15							/W
Operating Junction Temperature Range	T_J	-55 to +150							
Storage Temperature Range	T_{STG}	-55 to +150							

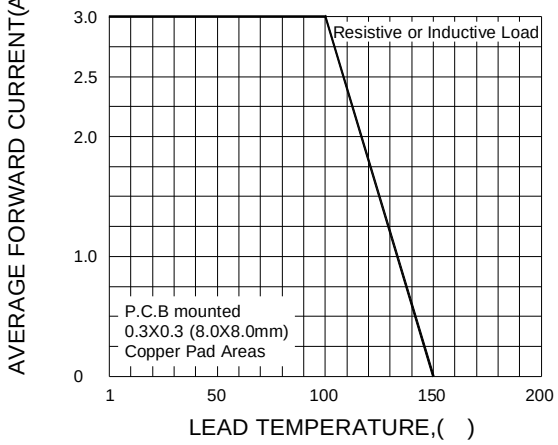
Notes:
1. Thermal resistance from Junction to ambient and from junction to lead mounted on PCB with 0.3×0.3″ (8.0 × 8.0mm) copper pad areas.
2. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts

CURRENT 3.0 Ampere
VOLTAGE RANG 50 to 1000 Volts

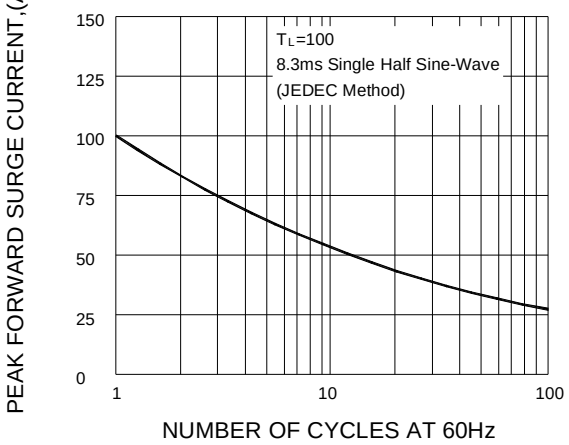
RS3ABF THRU RS3MBF

RATING AND CHRACTERISTIC CURVES RS3A Thru RS3M

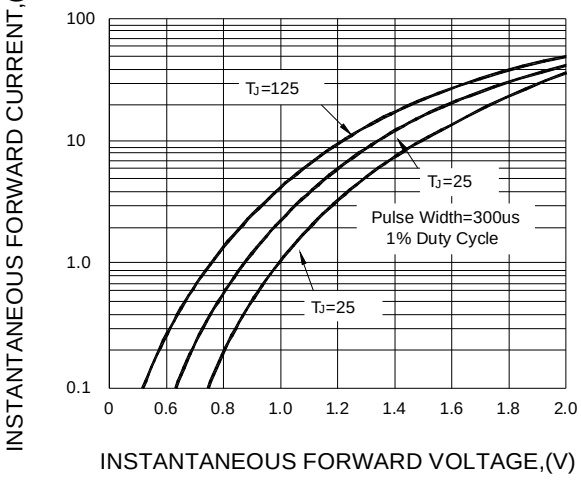
F1G.1-FORWARD CURRENT DERATING CURVE



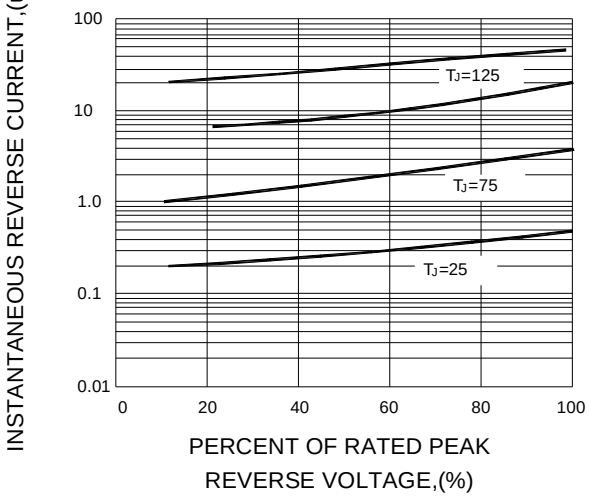
F1G.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



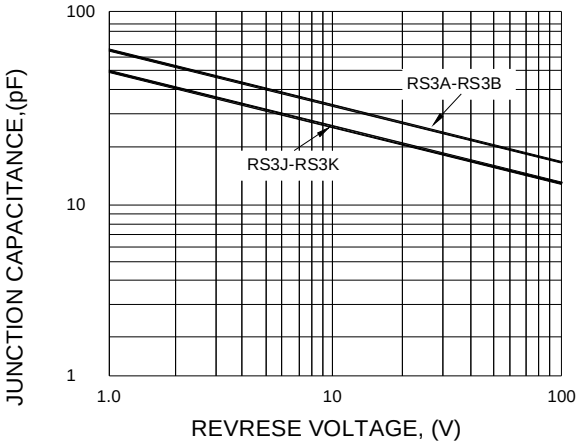
F1G.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



F1G.4-TYPICAL REVERSE CHARACTERISTICS



F1G.5-TYPICAL JUNCTION CAPACITANCE



F1G.6-TRANSIENT THERMAL IMPEDANCE

